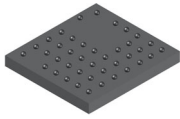
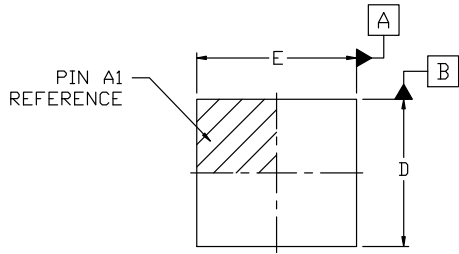


MECHANICAL CASE OUTLINE PACKAGE DIMENSIONS

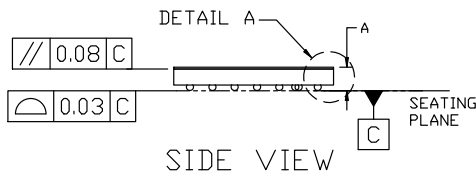


WLCSP40 2.301x2.499x0.369 CASE 567HU ISSUE 0

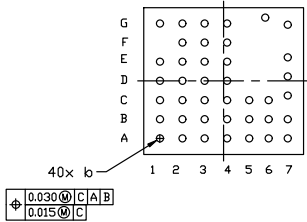
DATE 29 APR 2022



TOP VIEW

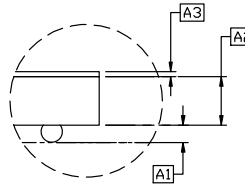


SIDE VIEW

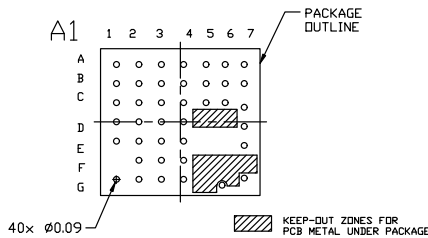


BOTTOM VIEW

DIM	MILLIMETERS		
	MIN.	NOM.	MAX.
A	0.333	0.369	0.405
A1	0.070	0.090	0.110
A2	0.254 REF		
A3	0.022	0.025	0.028
b	0.096	0.111	0.126
D	2.276	2.301	2.326
E	2.474	2.499	2.524



DETAIL A
SCALE 1:3



RECOMMENDED
MOUNTING FOOTPRINT

* For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

NOTES:

1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 2009.
2. CONTROLLING DIMENSION: MILLIMETERS
3. DIMENSION b IS MEASURED AT THE MAXIMUM SOLDER BALL DIAMETER PARALLEL TO DATUM C.
4. COPLANARITY APPLIES TO THE SPHERICAL CROWNS OF THE SOLDER BALLS.
5. DATUM C, THE SEATING PLANE, IS DEFINED BY THE SPHERICAL CROWNS OF THE SOLDER BALLS.

BALL POSITION TABLE					
BALL	X	Y	BALL	X	Y
A1	-1.00	-0.90	D1	-1.00	0.00
A2	-0.65	-0.90	D2	-0.65	0.00
A3	-0.30	-0.90	D3	-0.30	0.00
A4	0.05	-0.90	D4	0.05	0.00
A5	0.40	-0.90	D7	1.00	0.07
A6	0.70	-0.90	E1	-1.00	0.30
A7	1.00	-0.90	E2	-0.65	0.30
B1	-1.00	-0.60	E3	-0.30	0.30
B2	-0.65	-0.60	E4	0.05	0.30
B3	-0.30	-0.60	E7	1.00	0.37
B4	0.05	-0.60	F2	-0.65	0.60
B5	0.40	-0.60	F3	-0.30	0.60
B6	0.70	-0.60	F4	0.05	0.60
B7	1.00	-0.60	G1	-1.00	0.90
C1	-1.00	-0.30	G2	-0.65	0.90
C2	-0.65	-0.30	G3	-0.30	0.90
C3	-0.30	-0.30	G4	0.05	0.90
C4	0.05	-0.30	G6	0.65	0.99
C5	0.40	-0.30	G7	1.00	0.88
C6	0.70	-0.30			
C7	1.00	-0.23			

MOUNTING PAD POSITION TABLE					
BALL	X	Y	BALL	X	Y
A1	-1.00	0.90	D1	-1.00	0.00
A2	-0.65	0.90	D2	-0.65	0.00
A3	-0.30	0.90	D3	-0.30	0.00
A4	0.05	0.90	D4	0.05	0.00
A5	0.40	0.90	D7	1.00	-0.07
A6	0.70	0.90	E1	-1.00	-0.30
A7	1.00	0.90	E2	-0.65	-0.30
B1	-1.00	0.60	E3	-0.30	-0.30
B2	-0.65	0.60	E4	0.05	-0.30
B3	-0.30	0.60	E7	1.00	-0.37
B4	0.05	0.60	F2	-0.65	-0.60
B5	0.40	0.60	F3	-0.30	-0.60
B6	0.70	0.60	F4	0.05	-0.60
B7	1.00	0.60	G1	-1.00	-0.90
C1	-1.00	0.30	G2	-0.65	-0.90
C2	-0.65	0.30	G3	-0.30	-0.90
C3	-0.30	0.30	G4	0.05	-0.90
C4	0.05	0.30	G6	0.65	-0.99
C5	0.40	0.30	G7	1.00	-0.88
C6	0.70	0.30			
C7	1.00	0.23			

DOCUMENT NUMBER:	98AON44926H	Electronic versions are uncontrolled except when accessed directly from the Document Repository. Printed versions are uncontrolled except when stamped "CONTROLLED COPY" in red.
DESCRIPTION:	WLCSP40 2.301x2.499x0.369	PAGE 1 OF 1

onsemi and ONSEMI are trademarks of Semiconductor Components Industries, LLC dba onsemi or its subsidiaries in the United States and/or other countries. onsemi reserves the right to make changes without further notice to any products herein. onsemi makes no warranty, representation or guarantee regarding the suitability of its products for any particular purpose, nor does onsemi assume any liability arising out of the application or use of any product or circuit, and specifically disclaims any and all liability, including without limitation special, consequential or incidental damages. onsemi does not convey any license under its patent rights nor the rights of others.